

Abstract

PROCESSING SYSTEM AND METHOD FOR LARGE SCALE SUBSTRATES

- 5 An alignment assembly for aligning a plurality of IC units, the assembly comprising: a plate having vacuum apertures for receiving said IC units on an engagement surface; a first alignment member having a plurality of projections and recesses uniformly distributed along a first engagement edge; a second alignment member having a plurality of projections and recesses uniformly distributed along a second engagement
- 10 edge; said first and second alignment members in sliding contact with the engagement surface; wherein said first and second alignment members arranged to move relative to each other so as to intermesh said respective projections and recesses, said intermeshed projections and recesses arranged to define a linear array of rectangular apertures sized to fit said IC units in an aligned condition.

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Figure 1